

# **EPTC 2002 TECHNICAL COMMITTEES**

## **ADVANCED PACKAGING**

Mahadevan Iyer, *Institute of Microelectronics* – Chair  
Simon Chua, *Agere Systems*  
James How, *Motorola Electronics*  
Lim Thiam Beng, *Institute of Microelectronics*  
Jan Vardaman, *Tech Search, USA*

## **INTERCONNECTS AND ASSEMBLY**

Wang Zhiping, *Philips Mobile Display Systems, China* - Chair  
Hong Meng Ho, *IMEC, Belgium*  
James How, *Motorola Electronics*  
Kang En-Tang, *National University of Singapore*  
Charles Lee, *Infineon Technologies Asia Pacific*  
Mui Yew Cheong, *Advanced Micro Devices*  
Tan Ah Chin, *Micron Semiconductor Asia*  
Teo Poi Siong, *Institute of Microelectronics*  
Jenny Wu, *Anadigics, USA*

## **MATERIALS AND PROCESSES**

Joseph Arokiam, *Honeywell* - Chair  
W.T Chen, *ASE, USA*  
V. Kripesh, *Institute of Microelectronics*  
Charles Lee, *Infineon Technologies Asia Pacific*  
Tan Ah Chin, *Micron Semiconductor Asia*  
C.P. Wong, *Georgia Institute of Technology, USA*

## **MODELING AND SIMULATION**

Andrew Tay, *National University of Singapore* - Chair  
Leo Ernst, *Delft University of Technology, Netherlands*  
Lim Kian Ming, *National University of Singapore*  
Suresh Sitaraman, *Georgia Institute of Technology, USA*  
Tee Tong Yan, *ST Microelectronics*  
G Q Zhang, *Philips, Netherlands*

## **QUALITY AND RELIABILITY**

John Pang, *Nanyang Technological University*- Chair  
Lim Chwee Teck, *National University of Singapore*  
Andreas Schubert, *Fraunhofer IZM, Germany*  
Suresh Sitaraman, *Georgia Institute of Technology, USA*  
Swee Yong Khim, *Infiniti Solutions*  
Tee Tong Yan, *ST Microelectronics*

## **THERMAL / ELECTRICAL DESIGN AND ANALYSIS**

Toh Kok Chuan, *Nanyang Technological University* - Chair  
A Cangellaris, *University of Illinois, Urbana-Champaign, USA*  
Chai Chee Kiong, *Nanyang Technological University*  
Chan Poh Kiong, *DSO National Laboratories*  
Yogendra Joshi, *Georgia Institute of Technology, USA*  
D Pinjala, *Institute of Microelectronics*  
Mihai Rotaru, *Institute of Microelectronics*